



Material Content Data Sheet



Sales Product Name				IPD70N10S3L-12		Issued		24. January 2018	
MA#				MA001698776					
Package				PG-TO252-3-11		Weight*		373.32 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.833	1.56	1.56	15625	15625	
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173		
	non noble metal	iron	7439-89-6	0.215	0.06		577		
	non noble metal	copper	7440-50-8	215.017	57.60	57.68	575954	576704	
	non noble metal	aluminium	7429-90-5	3.873	1.04	1.04	10374	10374	
wire	non noble metal	aluminium	7429-90-5	3.873	1.04	1.04	10374	10374	
encapsulation	organic material	carbon black	1333-86-4	1.206	0.32		3230		
	plastics	epoxy resin	-	21.102	5.65		56525		
	inorganic material	silicondioxide	60676-86-0	98.274	26.32	32.29	263243	322998	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10018	10018	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244	
solder	non noble metal	tin	7440-31-5	0.094	0.03		252		
	noble metal	silver	7440-22-4	0.118	0.03		315		
	non noble metal	lead	7439-92-1	4.493	1.20	1.26	12034	12601	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	iron	7439-89-6	0.019	0.01		51		
	non noble metal	copper	7440-50-8	19.177	5.14	5.15	51370	51436	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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